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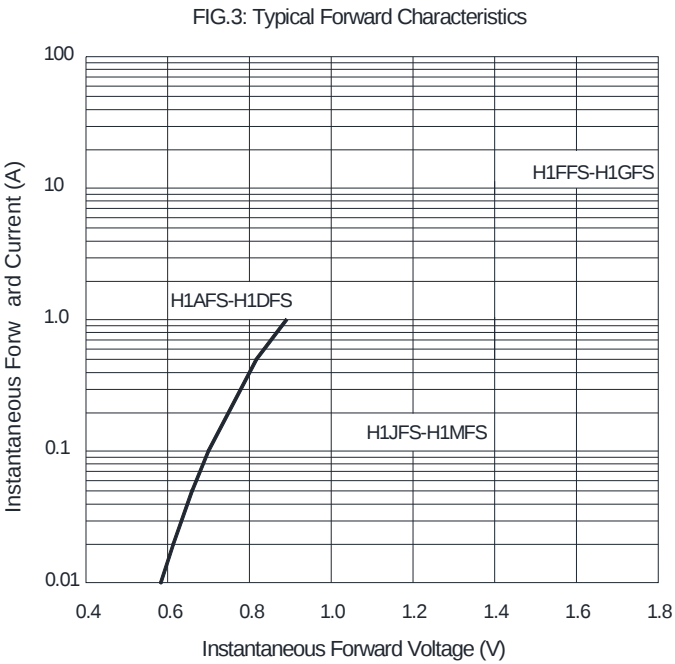
# H1AFS THRU H1MFS

Thermal Characteristics     $T_a=25$  - Unless otherwise specified

| PARAMETER                  | SYMBOL               | UNIT | H1AFS | H1BFS | H1DFS | H1GFS | H1JFS | H1KFS | H1MFS |
|----------------------------|----------------------|------|-------|-------|-------|-------|-------|-------|-------|
| Typical Thermal resistance | R J-A <sup>(1)</sup> | - /W | 75    |       |       |       |       |       |       |
|                            | R J-L <sup>(1)</sup> |      | 30    |       |       |       |       |       |       |
|                            | R J-C <sup>(1)</sup> |      | 25    |       |       |       |       |       |       |

Note:  
(1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

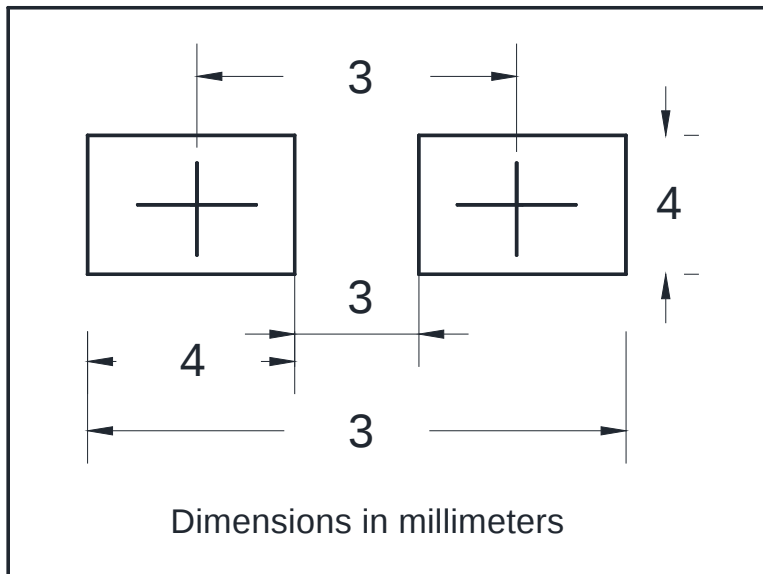
Characteristics (Typical)







## v Suggested pad layout



| SMAF |             |
|------|-------------|
| Dim  | Millimeters |
| P1   | 6.50        |
| P2   | 4.00        |
| P3   | 1.50        |
| Q1   | 2.50        |
| Q2   | 1.70        |

